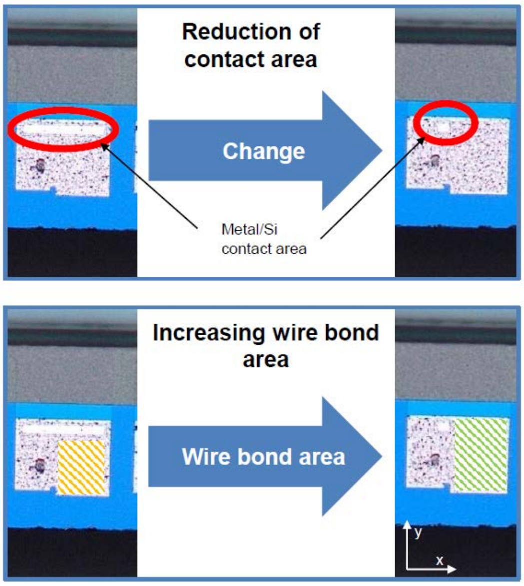
update Newsletter

November 27, 2020

PCN
Reduction of the contact windows within the bond areas for C38 pressure sensors

The bond areas of EPCOS C38 pressure sensor elements are divided into a wire bond area for contacting and a contact window that establishes the electrical connection to the piezoresistive resistors. To make the pressure sensor element even more robust against potential influences of subsequent processing steps in the customer application, these contact windows within the bond areas will be significantly reduced in the future. Since the total area of the bond pad is unchanged, an increased wire bond area will be available for our customers in future. This means that the C38 pressure sensor element can still be contacted using the familiar parameters, or the additional area can also be used. The reduced contact windows are already being used in other EPCOS pressure sensor elements such as C33 or C39 for the automotive sector.

Picture: Change of contact and bond area



The external shape or position of the bond areas are not changed.

Affected products

Ordering code
B58600E38*
B58601E38*

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Thermistors, Sensors
Internal / External

201127THERM1e

November 27, 2020

Scheduled date of change: March 1, 2021
Estimated date of first deliveries: March 1, 2021

The data sheets may be downloaded from
www.tdk-electronics.tdk.com/en/pressure_sensor_dies

Enclosure PCN (ID No. TPS T125/01)

Contact Martin Reckziegel, TPS PS PM, Berlin

Customers are asked to address inquiries directly to their sales contacts.

Product / Process Change Notification

1. ID No. PCN TPS T125/01

2. Date of announcement November 27, 2020

3. Product / product group	**Old ordering code**	**New ordering code**	**Customer part number**
all C38 products	unchanged	unchanged	unchanged

4. Description of change

C38: Reduction of contact area within bond pad

5. Effect on the product or for the customer (benefit, quality, specification, lead time)

Reduction of contact area within each bond pad.

No change on size or position of any bond pad.

No change of any material or process flow.

6. Quality assurance measures / risk assessment

No risk expected. Reduced contact area is already used in other TDK automotive products like pressure sensing element C33 or C39.

No functional impact.

7. Scheduled date of change March 1, 2021

8. Estimated date of first delivery of changed product March 1, 2021

If TDK Electronics AG does not receive notification to the contrary within a period of 10 weeks, TDK Electronics AG assumes that the customer agrees to the change.

☒ For an interim period we cannot rule out that old as well as new products will be shipped.

☐ Future shipments can consist of old and new products as the new changed product is used as an alternative to the old product.

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Customer feedback

Customer acknowledgement Signature